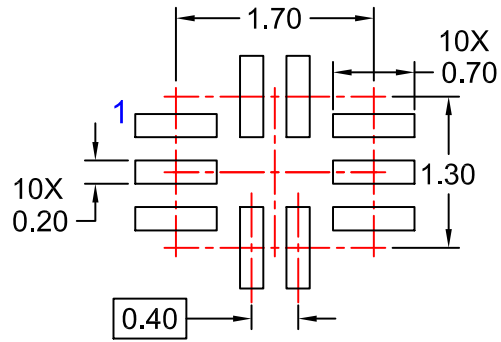
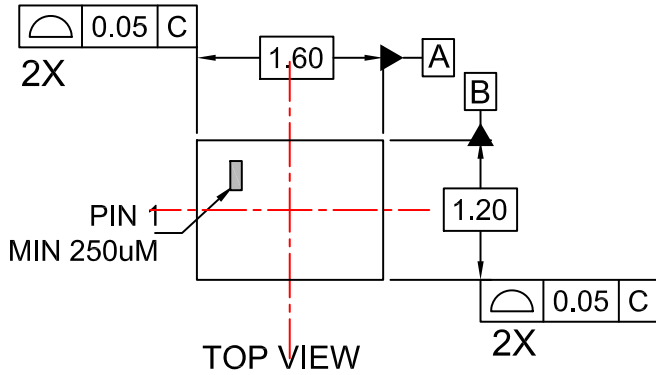


**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

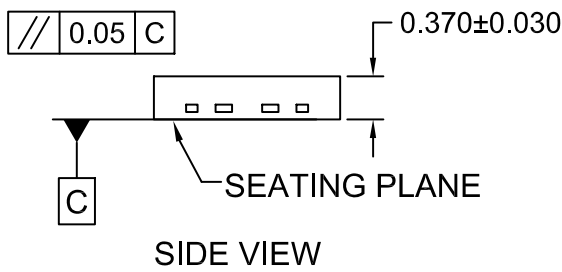


**X2QFN10 1.6x1.2, 0.4P**  
CASE 722AC  
ISSUE O

DATE 30 SEP 2016

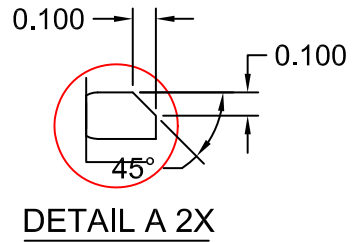
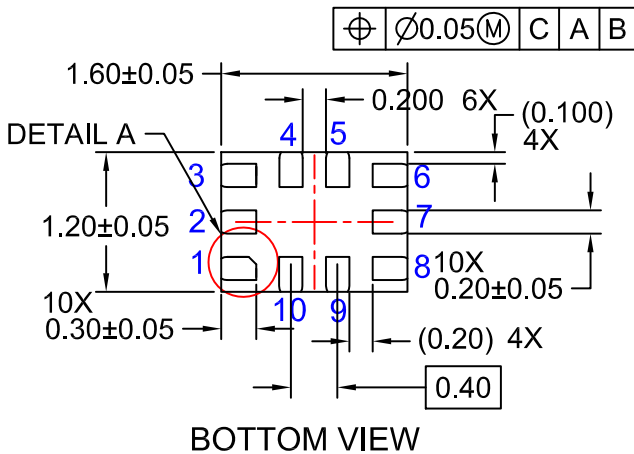


**LAND PATTERN RECOMMENDATION**



**NOTES:**

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 2009.
- D. PACKAGE NOMINAL HEIGHT IS 370 MICRONS.



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